# HI2220P601R-10

## **UNCONTROLLED DOCUMENT**

## PHYSICAL DIMENSIONS:

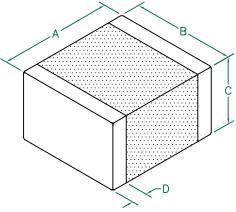
A 5.59 [.220] ± 0.51 [.020]

± 0.25 [.010] B 5.08 [.200]

<sup>±</sup> 0.25 [.010] C 3.05 [.120]

D 0.76 [.030] <sup>+</sup> 0.25 [.010]

Z vs FREQUENCY IMPEDANCE UNDER DC BIAS





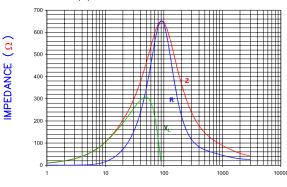
ELECTRICAL CHARACTERISTICS:							
Z @ 100MHz $\left(\begin{array}{c}\Omega\end{array}\right)$		DCR (Ω)	Rated Current				
Nominal	600						
Minimum	450						
Maximum	750	0.025	4000 mA				

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,000 PCS/REEL.
- 2. U.S. PATENT 5,821,846 AND 6,107,907 SHOULD APPEAR ON THE LABEL OF EACH REEL OF PACKAGED PARTS.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 5. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

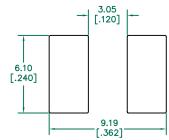
### |Z| , R, AND X vs. FREQUENCY

FREQUENCY (MHz)



FREQUENCY (MHz)

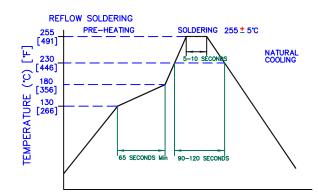
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.30) to this dimension.)

D

## RECOMMENDED SOLDERING CONDITIONS



01/12/01

HI2220P601R-10-E

DIMENSIONS ARE IN mm [INCHES] .			This print is the property of Laird		
			Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the		_
					2
					.u
			written consent of Laird Tech. All rights to design or invention are	_	
ADD OPERATING TEMPERATURE	08 /05 /13	OLL			
ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	00/03/13	ğ	PROJECT/PART NUMBER:	REV	PART T
UPDATE COMPANY LOGO ADD ROHS	01/24/08	JRK	HI2220P601R-10	F	CO-
CHANGE C DIMENSION FROM .130	05/11/04	JRK	11122201 00111 10	_	00-

01/12/01 BAC

DATE

ADD DC BIAS CURVE, CHG DCR RATING 03/19/03 JRK DATE:

ORIGINAL DRAFT

DESCRIPTION



AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3455

IMPEDANCE

